

At  
End  
4. (Amended) The imaging device of claim 7, further comprising leads connected to said semiconductor chip, said leads being partially encapsulated in said transparent plastic material.

---

7. (Amended) An imaging device, comprising:

B1  
a package formed of transparent plastic material;

At  
a semiconductor chip encapsulated within said package, said chip including an array of photosensitive elements for receiving an image and for generating corresponding signals, said photosensitive elements being covered by said transparent plastic material; and

an optical light transmitting device covering said photosensitive elements.

8. (Amended) The imaging device of claim 7, wherein said optical light transmitting device is formed of said transparent plastic material.

9. (Amended) The imaging device of claim 7 wherein said optical light transmitting device is a color filter, said filter being formed of said transparent plastic material.

---

11. (Amended) An imaging system, comprising:

B1  
a system for transmitting an image including an image source and a first semiconductor device,

At  
Cont.  
said image source capable of simultaneously transmitting an image to a plurality of semiconductor devices;

wherein said plurality of semiconductor devices includes first, second and third semiconductor devices for receiving the image and for generating corresponding signals; and first, second and third packages for protecting and supporting each said first second and third semiconductor device, said packages being formed of transparent plastic material,

a3  
End said plastic material including injection molded resin for transmitting an image from said image source onto said first, second and third semiconductor devices.

---

a4 13. (Amended) The system of claim 11 wherein said first, second and third semiconductor devices include complementary color filters.

---

28. (Amended) An imaging device, comprising:

a package formed of a housing, wherein said housing is formed of a ceramic material, and a transparent plastic cover;

1  
a2 a semiconductor chip located within said package, said chip including an array of photosensitive elements for receiving an image and for generating corresponding signals, said photosensitive elements being covered by said transparent plastic cover; and

an optical light transmitting device covering said photosensitive elements.

---

Please add new claim 32 as follows:

---

a6 32. (New) The imaging device of claim 7, wherein said optical light transmitting device is a lens, said lens being formed of said transparent plastic material.

---